



Material Content Data Sheet



Sales Product Name		IPD80R1K0CE		Issued		4. October 2018		
MA#		MA001609822						
Package		PG-TO252-3-341		Weight*		389.70 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.945	1.27	1.27	12688	12688
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		176	
	non noble metal	iron	7439-89-6	0.229	0.06		588	
	non noble metal	copper	7440-50-8	228.946	58.75	58.83	587495	588259
	non noble metal	aluminium	7429-90-5	0.429	0.11	0.11	1101	1101
wire	non noble metal	aluminium	7429-90-5	0.429	0.11	0.11	1101	1101
encapsulation	organic material	carbon black	1333-86-4	0.383	0.10		983	
	plastics	epoxy resin	-	11.619	2.98		29816	
	inorganic material	silicondioxide	60676-86-0	115.682	29.68	32.76	296848	327647
leadfinish	non noble metal	tin	7440-31-5	3.740	0.96	0.96	9597	9597
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1306	1306
solder	non noble metal	tin	7440-31-5	0.079	0.02		203	
	noble metal	silver	7440-22-4	0.099	0.03		253	
	non noble metal	lead	7439-92-1	3.769	0.97	1.02	9671	10127
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	iron	7439-89-6	0.019	0.00		49	
	non noble metal	copper	7440-50-8	19.177	4.92	4.92	49211	49275
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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